

ABSTRACT OF THE DISCLOSURE

A multi-chip image sensor module includes a first substrate; a photosensitive chip arranged on an upper surface of the first substrate; a lens holder mounted on the upper surface of the first substrate to encapsulate the photosensitive chip; a
5 lens barrel arranged within the lens holder and formed with a chamber and an opening communicating with the chamber; an aspheric lens and a transparent layer placed within the chamber; a second substrate mounted on the first substrate and electrically connected to the first substrate; and a lower chip located on a second surface of the second substrate.

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